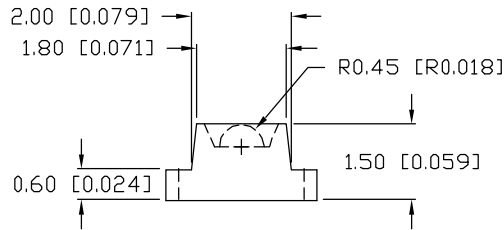
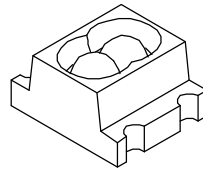
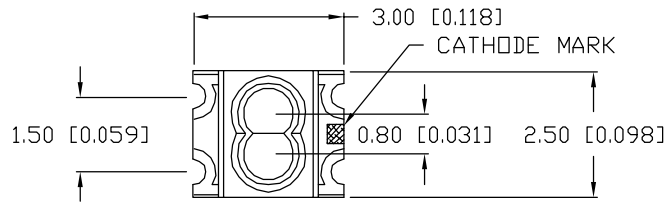


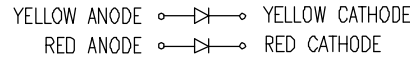
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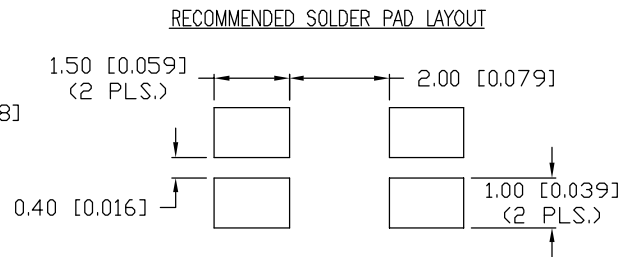
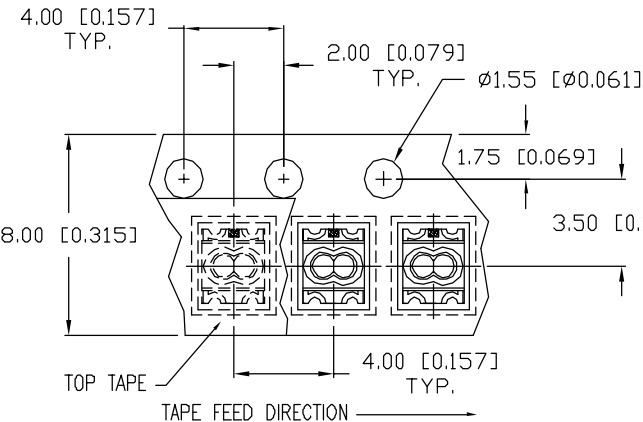
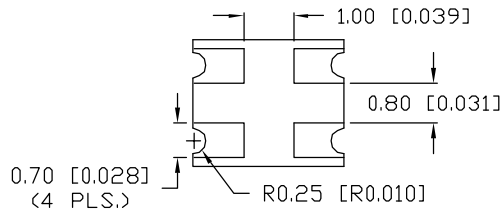
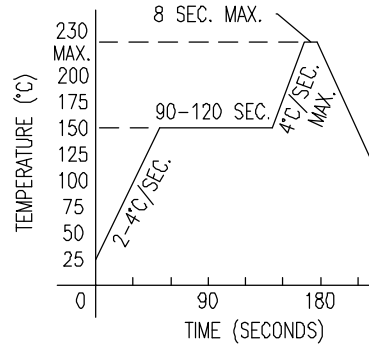
REV.  
E



TOP VIEW POLARITY



REFLOW PROFILE



ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=20\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		660 (RED)		nm	
		590 (YELLOW)		nm	
FORWARD VOLTAGE (R/Y)		1.7/2.1	2.2/2.5	V <sub>f</sub>	
REVERSE VOLTAGE	5.0			V <sub>r</sub>	I <sub>r</sub> =100μA
AXIAL INTENSITY (R/Y)		50/90		mcd	I <sub>f</sub> =20mA
VIEWING ANGLE		60		2x theta	
EMITTED COLOR:	RED/YELLOW				
EPOXY LENS FINISH:	WATER CLEAR				

LIMITS OF SAFE OPERATION AT 25°C

PARAMETER	COLORS	MAX	UNITS
PEAK FORWARD CURRENT*		160	mA
STEADY CURRENT		25	mA
POWER DISSIPATION	(R/Y)	60/100	mW
DERATE FROM 25°C		-1.0	mW/°C
OPERATING TEMP.		-40 TO +85	°C
STORAGE TEMP.		-40 TO +90	°C

\*  $t < 10\mu\text{s}$

NOTES:

1. THE POLARITY MARK IS ORIENTED TOWARDS THE TAPE SPROCKET HOLE.

CAUTION: MOISTURE SENSITIVE DEVICE  
PER JEDEC LEVEL 4 STANDARDS

UNCONTROLLED DOCUMENT

\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X=±1 (±0.039), X.X=±0.5 (±0.020), X.XX=±0.25 (±0.010), X.XXX=±0.127 (±0.005). LEAD SIZE=±0.05 (±0.002), LEAD LENGTH=±0.75 (±0.030). MIN.=+DECIMAL PRECISION MAX.=+0.00 -DECIMAL PRECISION

REV. E PART NUMBER SML-LXL1210SRSYCTR

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290 E. HELEN ROAD  
PALATINE, IL 60067-6976  
PHONE: +1.847.359.2790  
US WEB: www.lumex.com  
TW WEB: www.lumex.com.tw

2.7mm x 3.0mm PCB, SURFACE MOUNT LED,  
SUPER RED/SUPER YELLOW CHIPS,  
WATER CLEAR LENS, TAPE AND REEL.

RELIABILITY NOTE  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY: CT CHECKED BY: APPROVED BY: DATE: 10.14.97  
PAGE: 1 OF 1  
SCALE: N/A